

# Dual 2-Input AND Gate

## NL27WZ08

The NL27WZ08 is a high performance dual 2-input AND Gate operating from a 1.65 V to 5.5 V supply.

### Features

- Designed for 1.65 V to 5.5 V  $V_{CC}$  Operation
- 2.5 ns  $t_{PD}$  at  $V_{CC} = 5$  V (typ)
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- $I_{OFF}$  Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in US8, UDFN8 and UQFN8 Packages
- Chip Complexity < 100 FETs
- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol

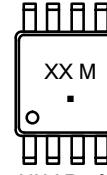


US8  
US SUFFIX  
CASE 493

### MARKING DIAGRAMS



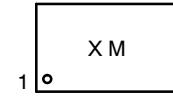
Commercial



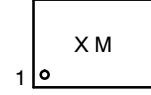
NLV Prefix



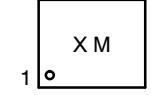
UDFN8, 1.95x1.0  
MU1 SUFFIX  
CASE 517CA



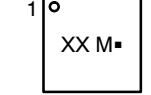
UDFN8, 1.6x1.0  
MU2 SUFFIX  
CASE 517BY



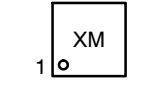
UDFN8, 1.45x1.0  
MU3 SUFFIX  
CASE 517BZ



UQFN8, 1.6x1.6  
MQ1 SUFFIX  
CASE 523AN



UQFN8, 1.4x1.2  
MQ2 SUFFIX  
CASE 523AS



X, XX, XXXX = Specific Device Code

A = Assembly Location

L = Lot Code

Y = Year Code

W = Week Code

M = Date Code

▪ = Pb-Free Package

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

# NL27WZ08

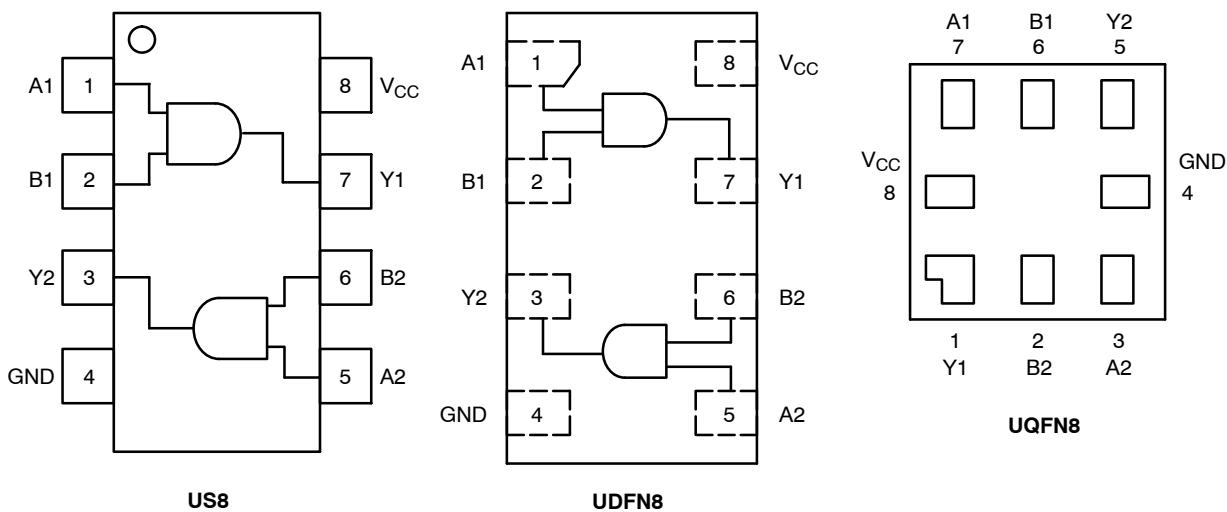


Figure 2. Pinout

## PIN ASSIGNMENT (US8 / UDFN8)

Pin	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V <sub>CC</sub>

## PIN ASSIGNMENT (UQFN8)

Pin	Function
1	Y1
2	B2
3	A2
4	GND
5	Y2
6	B1
7	A1
8	V <sub>CC</sub>

## FUNCTION TABLE Y = AB

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

H = HIGH Logic Level  
L = LOW Logic Level

## MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
$V_{CC}$	DC Supply Voltage	-0.5 to +6.5	V
$V_{IN}$	DC Input Voltage	-0.5 to +6.5	V
$V_{OUT}$	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ( $V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +6.5 -0.5 to +6.5	V
$I_{IK}$	DC Input Diode Current $V_{IN} < GND$	-50	mA
$I_{OK}$	DC Output Diode Current $V_{OUT} < GND$	-50	mA
$I_{OUT}$	DC Output Source/Sink Current	$\pm 50$	mA
$I_{CC}$ or $I_{GND}$	DC Supply Current per Supply Pin or Ground Pin	$\pm 100$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	°C
$T_L$	Lead Temperature, 1 mm from Case for 10 secs	260	°C
$T_J$	Junction Temperature Under Bias	+150	°C
$\theta_{JA}$	Thermal Resistance (Note 2)	US8 UQFN8 UDFN8 250 210 231	°C/W
$P_D$	Power Dissipation in Still Air	US8 UQFN8 UDFN8 500 595 541	mW
MSL	Moisture Sensitivity	Level 1	-
$F_R$	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
$V_{ESD}$	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model 2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)	$\pm 100$	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
$V_{CC}$	Positive DC Supply Voltage	1.65	5.5	V
$V_{IN}$	DC Input Voltage	0	5.5	V
$V_{OUT}$	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ( $V_{CC} = 0$ V)	0 0 0	$V_{CC}$ 5.5 5.5	
$T_A$	Operating Temperature Range	-55	+125	°C
$t_r, t_f$	Input Rise and Fall Time $V_{CC} = 1.65$ V to 1.95 V $V_{CC} = 2.3$ V to 2.7 V $V_{CC} = 3.0$ V to 3.6 V $V_{CC} = 4.5$ V to 5.5 V	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-55°C ≤ T <sub>A</sub> ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95	0.65 x V <sub>CC</sub>			0.65 x V <sub>CC</sub>		V
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>		
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	V
			2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OH</sub>	High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -100 μA I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA I <sub>OH</sub> = -12 mA I <sub>OH</sub> = -16 mA I <sub>OH</sub> = -24 mA I <sub>OH</sub> = -32 mA	1.65 to 5.5	V <sub>CC</sub> - 0.1 1.65 1.29 1.4 2.3 1.9 2.1 2.7 2.2 2.4 3.0 2.4 2.7 3.0 2.3 2.5 4.5 	V <sub>CC</sub> 1.29 1.4 — — 1.9 2.1 2.7 2.2 	— — — — — 	V <sub>CC</sub> - 0.1 1.29 — — 1.9 — 2.2 2.4 — 2.4 — 2.7 — 2.3 — 3.8 —	— — — — — 	V
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA I <sub>OL</sub> = 12 mA I <sub>OL</sub> = 16 mA I <sub>OL</sub> = 24 mA I <sub>OL</sub> = 32 mA	1.65 to 5.5	— 1.65 — — — — — — — — — — — — — — —	— 0.08 0.2 0.3 0.22 0.4 — 0.28 0.4 — 0.38 0.55 — 0.42 0.55 —	0.1 0.24 0.3 0.4 0.4 0.4 — 0.55 — 0.55 — 0.55 — — — —	— — — — — — — — — — — — — — — — —	0.1 0.24 0.3 0.4 0.4 0.4 — 0.55 — 0.55 — 0.55 — — — —	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	1.65 to 5.5	—	—	0.1	—	±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0	—	—	1.0	—	10	μA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	1.0	—	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

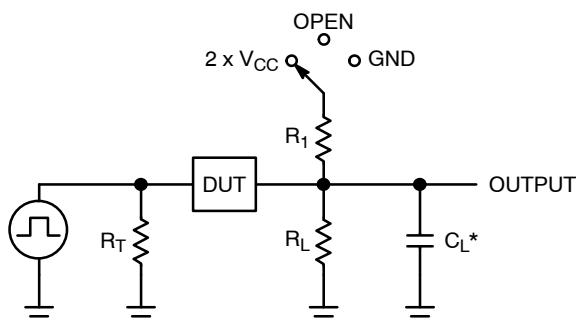
## AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	Test Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55 to 125°C		Units
				Min	Typ	Max	Min	Max	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay, (A or B) to Y	1.65 to 1.95	C <sub>L</sub> = 15 pF R <sub>L</sub> = 1 MΩ R <sub>1</sub> = Open	—	5.7	10.5	—	11.0	ns
		2.3 to 2.7		—	3.5	5.8	—	6.2	
		3.0 to 3.6		—	2.6	3.9	—	4.3	
		4.5 to 5.5		—	1.9	3.1	—	3.3	
		3.0 to 3.6	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, R <sub>1</sub> = Open	—	3.2	4.8	—	5.2	
		4.5 to 5.5		—	2.5	3.7	—	4.0	

## CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	2.5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	9 11	pF

5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.



$C_1$  includes probe and jig capacitance

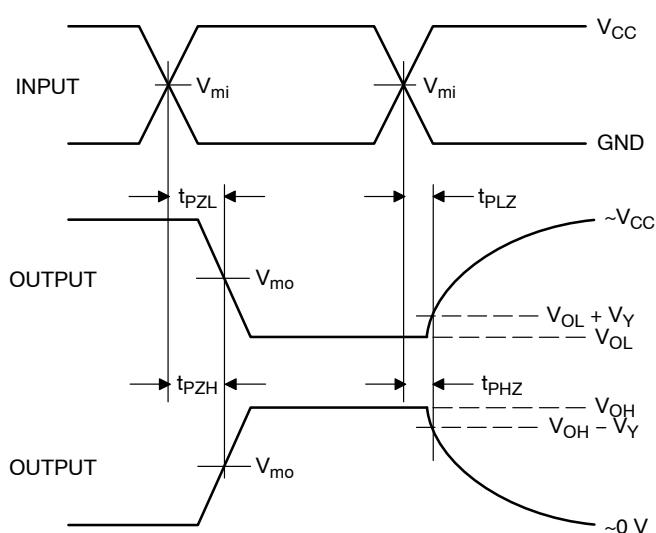
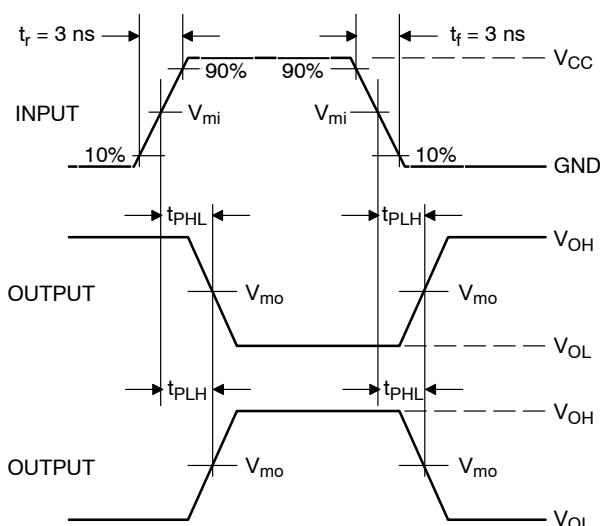
$Z_{\text{out}}$  is  $Z_{\text{out}}$  of pulse generator (typically  $50 \Omega$ )

R is 200  
f = 1 MHz

**Figure 3. Test Circuit**

Test	Switch Position	$C_L$ , pF	$R_L$ , $\Omega$	$R_1$ , $\Omega$
$t_{PLH} / t_{PHL}$	Open	See AC Characteristics Table		
$t_{PLZ} / t_{PZL}$	$2 \times V_{CC}$	50	500	500
$t_{PHZ} / t_{PZH}$	GND	50	500	500

X = Don't Care



**Figure 4. Switching Waveforms**

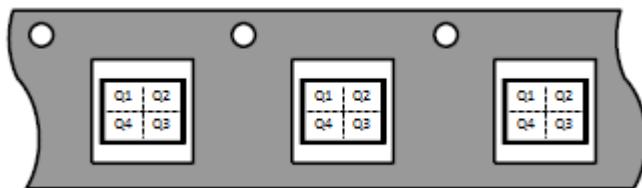
V <sub>CC</sub> , V	V <sub>mi</sub> , V	V <sub>mo</sub> , V		V <sub>Y</sub> , V
		t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub> , t <sub>PZH</sub> , t <sub>PHZ</sub>	
1.65 to 1.95	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
2.3 to 2.7	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
3.0 to 3.6	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3
4.5 to 5.5	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3

**DEVICE ORDERING INFORMATION**

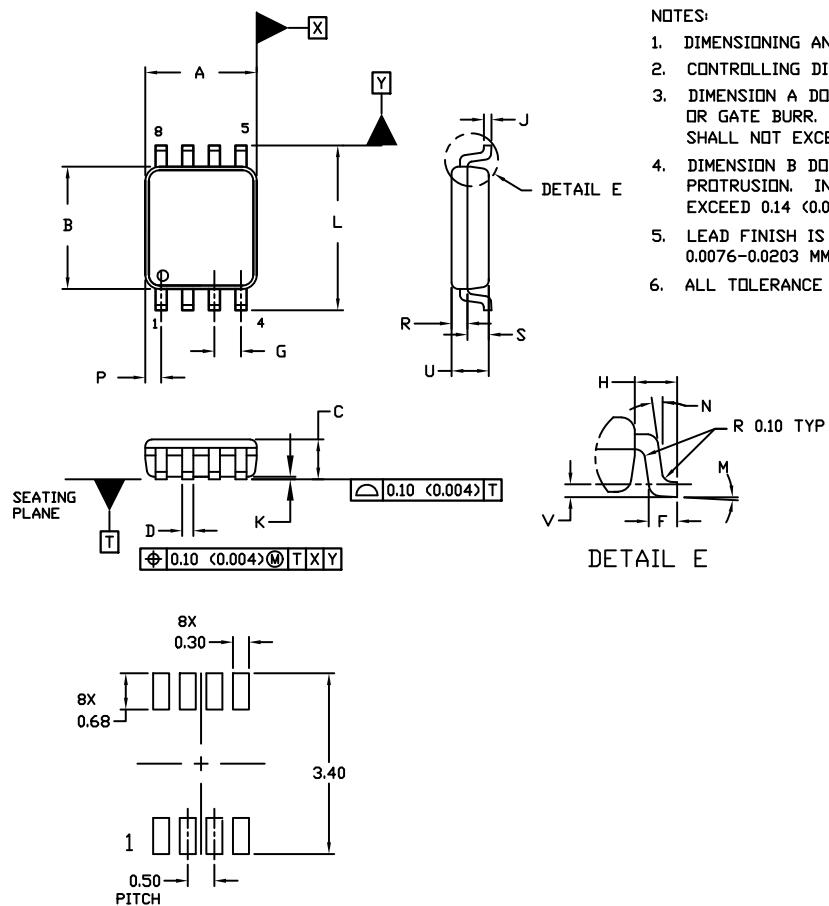
Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
NL27WZ08USG	US8	L2	Q4	3000 / Tape & Reel
NL27WZ08USG-Q* (Please contact <b>onsemi</b> )	US8	L2	Q4	3000 / Tape & Reel
NL27WZ08MQ1TCG	UQFN8, 1.6 x 1.6, 0.5P	AD	Q1	3000 / Tape & Reel
NL27WZ08MU1TCG	UDFN8, 1.95 x 1.0, 0.5P	AH	Q4	3000 / Tape & Reel
NL27WZ08MU1TWG	UDFN8, 1.95 x 1.0, 0.5P	AK	Q1	3000 / Tape & Reel
NL27WZ08MU3TCG	UDFN8, 1.45 x 1.0, 0.35P	F	Q4	3000 / Tape & Reel
NL27WZ08MU2TCG	UDFN8, 1.6 x 1.0, 0.4P	AJ	Q4	3000 / Tape & Reel
NL27WZ08MQ2TCG (Please contact <b>onsemi</b> )	UQFN8, 1.4 x 1.2, 0.4P	TBD	TBD	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

**Pin 1 Orientation in Tape and Reel****Direction of Feed**

## PACKAGE DIMENSIONS

US8  
CASE 493  
ISSUE F

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION, OR GATE BURR. MOLD FLASH, PROTRUSION, OR GATE BURR SHALL NOT EXCEED 0.14 (0.0055") PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.14 (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM (0.003-0.008").
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED  $\pm 0.0508$  MM (0.002").

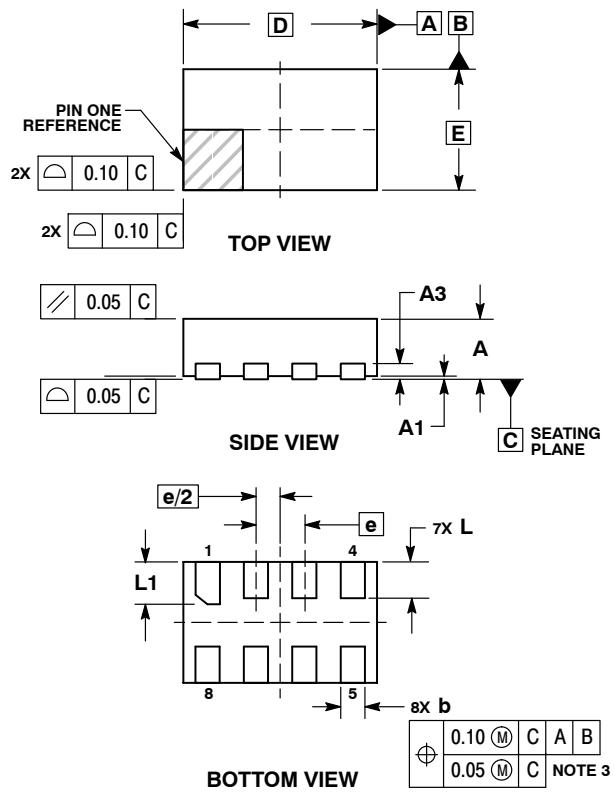
DIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020	BSC
H	0.40	REF	0.016	REF
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.25	0.118	0.128
M	0°	6°	0°	6°
N	0°	10°	0°	10°
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12	BSC	0.005	BSC

RECOMMENDED \*  
MOUNTING FOOTPRINT

\* For additional information on our Pb-Free  
process and reflow details, please  
download the ON Semiconductor Soldering and  
Mounting Techniques Reference Manual,  
SOLDEERW/D.

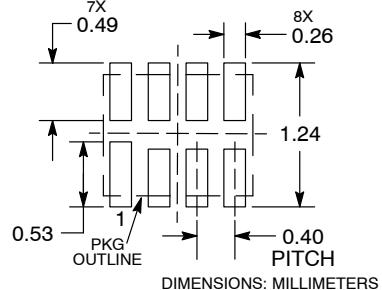
## PACKAGE DIMENSIONS

UDFN8, 1.6x1, 0.4P  
CASE 517BY  
ISSUE O



DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.60 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.30	0.40

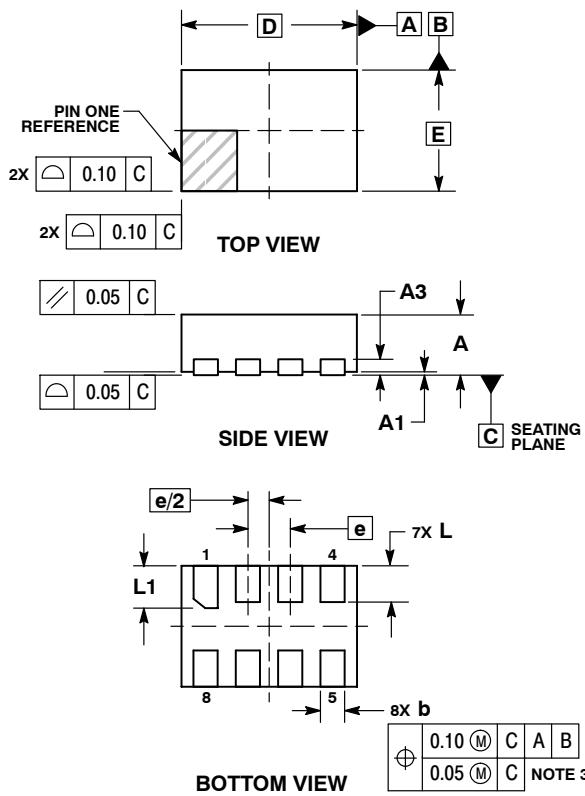
**RECOMMENDED  
SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

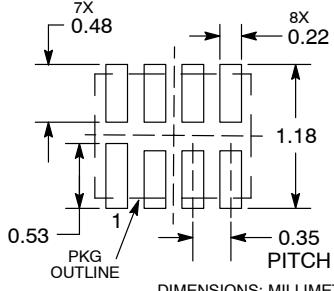
## UDFN8, 1.45x1, 0.35P

CASE 517BZ  
ISSUE O

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED  
SOLDERING FOOTPRINT\*

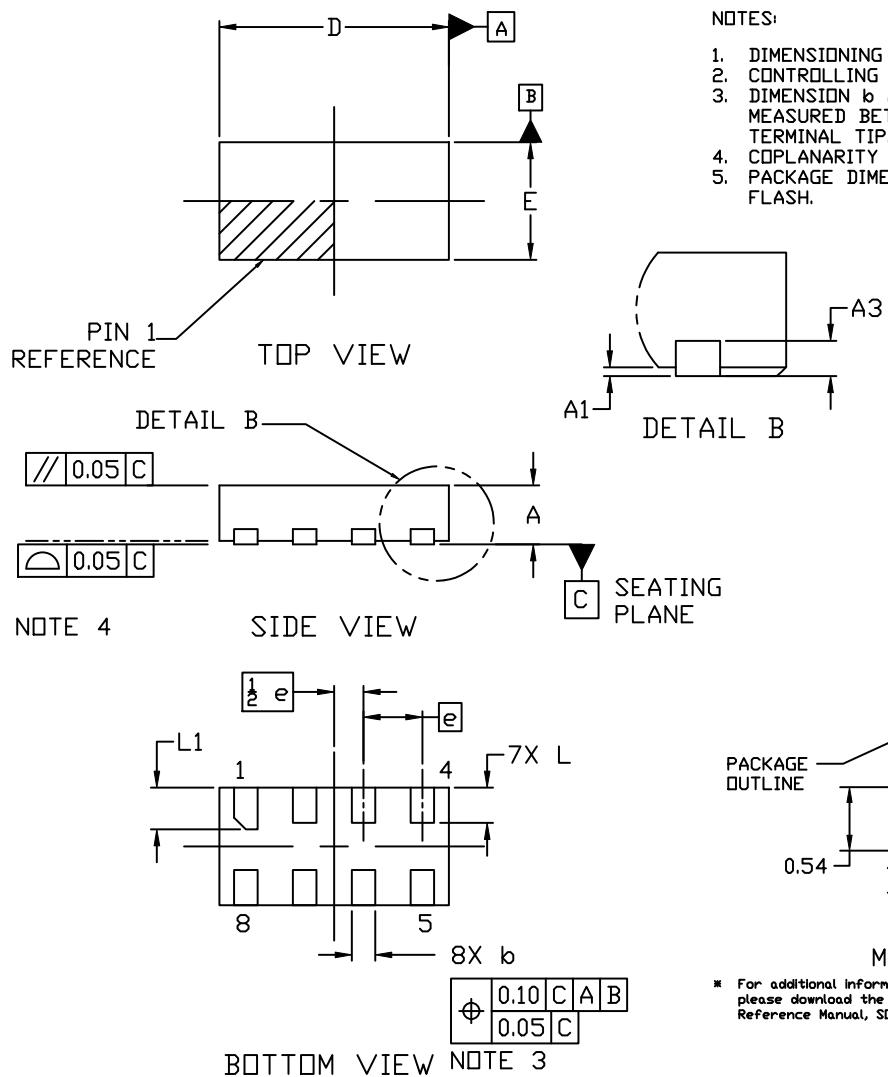
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

UDFN8, 1.95x1.0, 0.5P

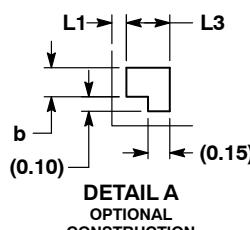
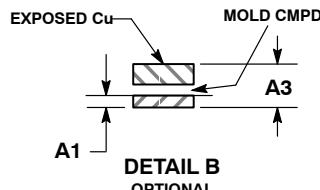
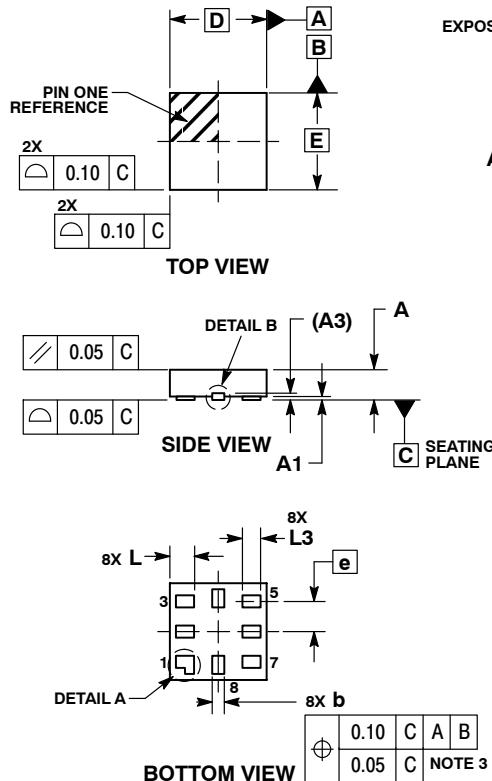
CASE 517CA

ISSUE A



## PACKAGE DIMENSIONS

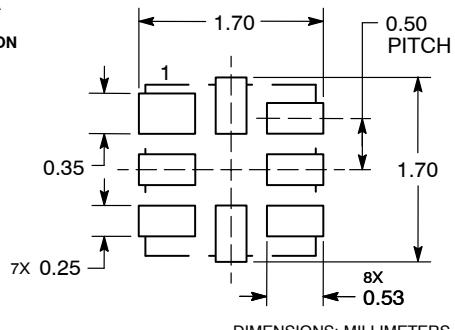
**UQFN8, 1.6x1.6, 0.5P**  
**CASE 523AN**  
**ISSUE O**



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

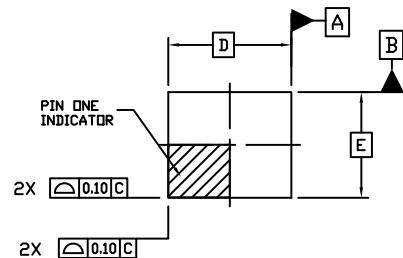
DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.60 BSC	
E	1.60 BSC	
e	0.50 BSC	
L	0.35	0.45
L1	---	0.15
L3	0.25	0.35

**SOLDERING FOOTPRINT\***

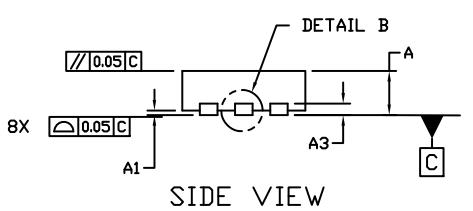
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

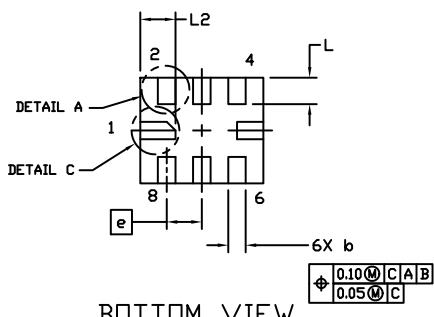
**UQFN8, 1.4x1.2, 0.4P**  
CASE 523AS  
ISSUE B



TOP VIEW



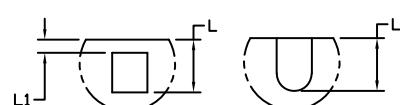
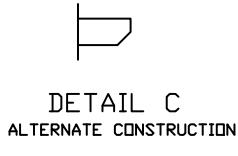
SIDE VIEW



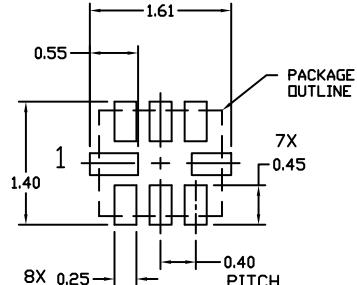
BOTTOM VIEW

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. REFER TO SPECIFIC DEVICE DATA SHEET FOR PIN 1 NOTCH LOCATION.

DETAIL B  
ALTERNATE CONSTRUCTIONDETAIL A  
ALTERNATE CONSTRUCTIONS

NOTE 4

RECOMMENDED  
MOUNTING FOOTPRINT \*

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERMM/D.

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